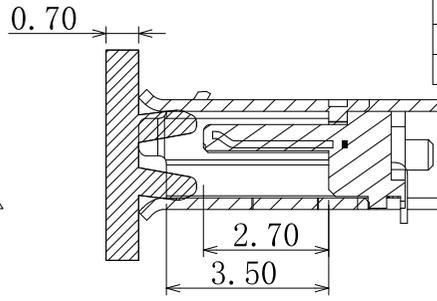
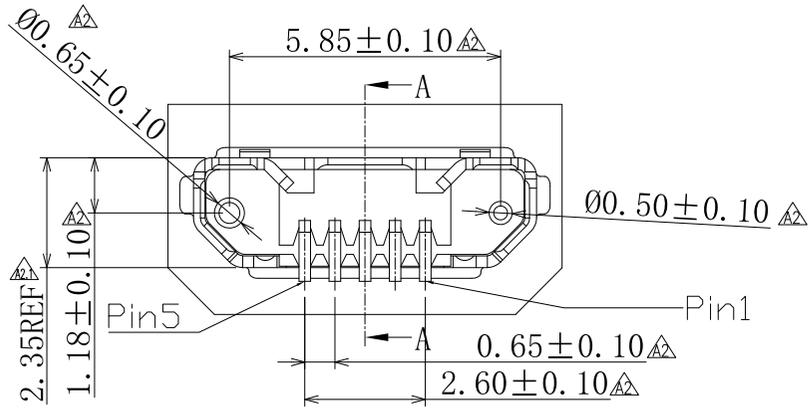


# GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2020/03/19	Hanson
A1			Change Shell Plating	2021/04/02	Hanson
A2			Add DIM.	2022/01/26	Ken Lin
A2.1			Add DIM.	2022/12/05	Ken Lin
A2.2			操作溫度符工規規格, Note Change	2025/07/09	Ken Lin



剖视图A-A

Note:

Material:

Housing: LCP UL94V-0

Contact: C2680R-H, T=0.15mm,

Plating: NI 50U", AU 10U"

△ Shell: SUS201T=0.25mm, Plating: MatteTin 60U"

Specification:

Current rating: Pin1 Pin5 1.8A Max, Other 1.0A.

Dielectric withstanding

voltage: 100 V(ac) for 1 min.

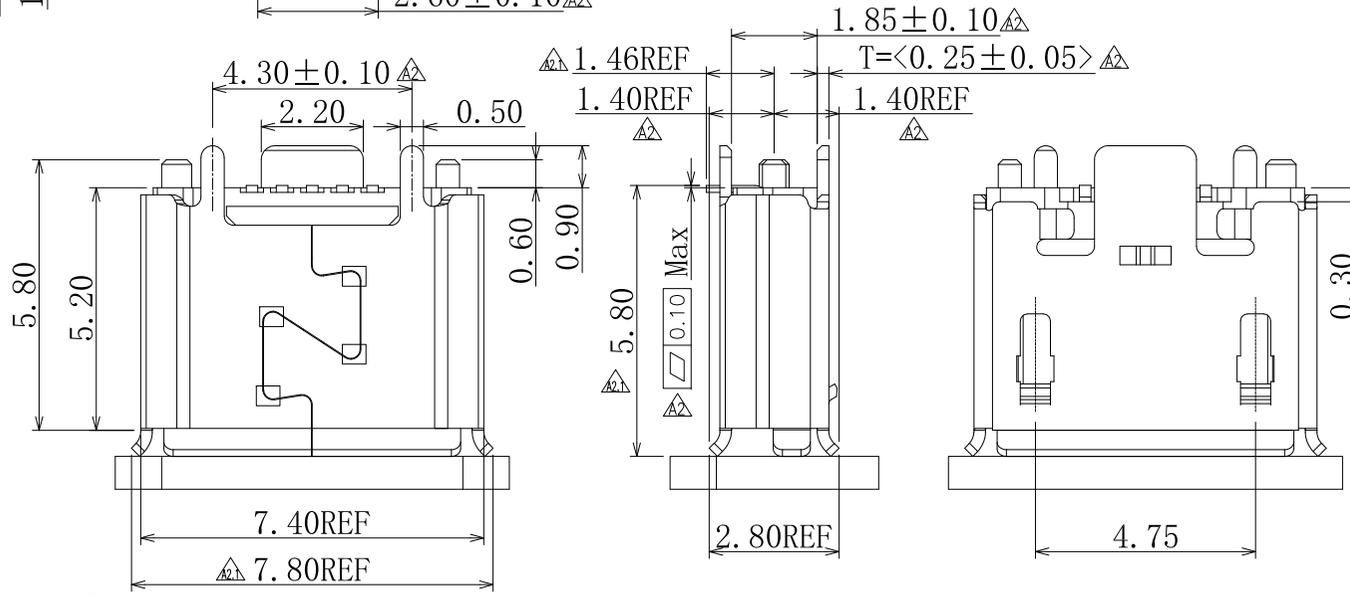
Contact resistance: 50 mW, Max.

Insulation resistance: 100 MW, Min.

Total mating force: 3.57 Kgf Max.

Total unmating force: 1.0 Kgf Min

△ Temperature range: -40° C To +85° C



MATRIX PART NO:

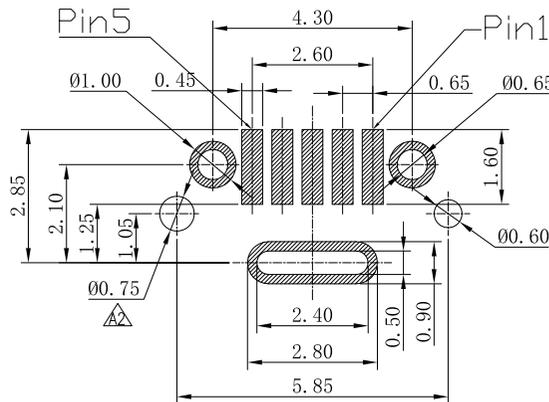
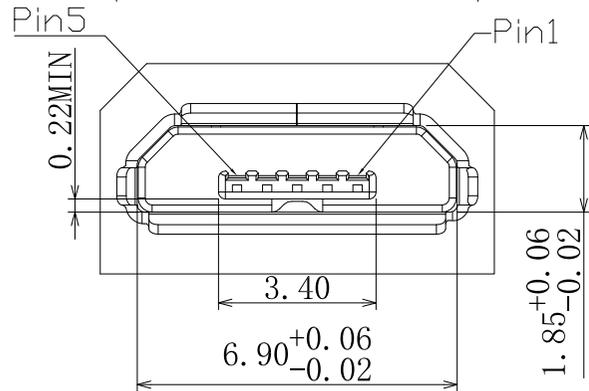
MUSB 05-10-460

Matrix-USB

Pin number

Series Number

Gold Plating:  
01=Gold Flash  
10=10u  
30=30u



RECOMMENDED PCB LAYOUT



Matrix Electronics Co., Ltd

TOLERANCE:		DESIGN BY :	DATE :	PART NAME:	
X:X	±0.25	Ken Lin	2025/07/09	Micro USB Type B SMT Female 直立式	
X:XX	±0.15	CHECKED BY:	DATE :	PART NO.	MUSB05-10-460
X:XXX	±0.08	Hanson Huang	2025/07/09	MOLD NO.	NA
ANGLE: ±2°		APPROVED BY1:	DATE :	DRAW NO.	
		Richard Hsieh	2025/07/09	SHEET NO.	1 OF 1
		APPROVED BY2:	DATE :		
		Richard Hsieh	2025/07/09		



UNIT: mm [inch]

SCALE:1:1 SIZE:A4